


ChipletCore

# 2027 MCSoC-ChipletCore Global Summit

on Chiplet Architectures and Heterogeneous 3D Integration

20th ANNIVERSARY

**Hosted within the 20th IEEE MCSoC 2027 | May 10–13, 2027 | Tokyo, Japan**

The 2027 MCSoC–ChipletCore Global Summit is a dedicated venue for advancing chiplet-based architectures, heterogeneous 3D integration, and die-to-die interconnect systems. It brings together researchers, semiconductor architects, EDA developers, and industry practitioners to explore the principles, standards, and packaging technologies that enable modular, multi-die Systems-on-Chip in the post-Moore era: from die-to-die protocols and 2.5D/3D packaging to thermal and power co-design, open chiplet ecosystems, and system-level integration for AI, edge, and cloud computing.

## Topics of Interest

**Track 1** Chiplet-Based Multicore and Many-Core System Architectures

**Track 2** Die-to-Die Interconnects, Protocols, and Network-on-Package (NoP)

**Track 3** 2.5D/3D Heterogeneous Integration and Advanced Packaging

**Track 4** Thermal Management, Power Delivery, and Signal Integrity in Multi-Die Systems

**Track 5** EDA Tools, Modeling, and Co-Design Flows for Chiplets

**Track 6** Testing, Known-Good-Die (KGD), Reliability, and Fault Tolerance

**Track 7** Hardware Security, Trust, and Supply-Chain Integrity in Chiplet Ecosystems

**Track 8** Heterogeneous Chiplets for AI, Neuromorphic, and Embodied Systems

*Track chairs and detailed topics: please see the summit website.*

## Summit Chairs

**SUMMIT CHAIR**
**Lichen Weng**
Tenstorrent Inc., USA

**SUMMIT CO-CHAIR**
**Chun-Ming Huang**
Taiwan Semiconductor Research Institute (TSRI), Taiwan

## Important Dates (Round 1)

Paper Submission
**December 31, 2026**

Notification
**January 31, 2027**

Camera-Ready & Registration
**February 10, 2027**

## Paper Submission

Submit via EDAS, selecting the **ChipletCore** track:
**https://edas.info/N35724**

Proceedings published in IEEE Xplore and indexed by Scopus.

## Why Participate in ChipletCore?

**Keynote Talks**
Insights from leading experts in academia and industry.

**Global Community**
Connect with researchers and industry leaders worldwide.

**IEEE Proceedings**
Regular and short papers published in IEEE Xplore.

**20th Anniversary**
Celebrate two decades of the MCSoC Forum in Tokyo.

**Scan for tracks, chairs, and full details**
mcsoc-forum.org/2027/index.php/chipletcore/

Scopus Indexed

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## Patron, Host, and Sponsorships

GIATEC — ADVANCED INFORMATICS TECHNOLOGY

MULTICORE/MANY-CORE SYSTEMS-ON-CHIP

UEC TOKYO

THE UNIVERSITY OF AIZU — Advance Knowledge for Humanity — 1993

ASL — Adaptive Sustainable Life

IEEE COMPUTER SOCIETY

80th ANNIVERSARY CELEBRATION

IEEE TCMM — Technical Committee on Microprocessors and Microcomputers